

CTL_embedded NAND Code Information(1/3)

Last Updated : November 2008

K **L** **X** **X** **X** **X** **X** **X** **X** **X** **-** **X** **X** **X** **X** **X** **X** **X**

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. MOVI NAND/MCP : L

CTL : Controller

3. NAND Function

E : Error Free NAND L : LBA NAND
 S : eSSD M : moviNAND
 C : Cartridge SIP

4~5. embedded NAND Density

28 : 128M Byte 56 : 256M Byte
 12 : 512M Byte 1G : 1G Byte
 2G : 2G Byte 3G : 3G Byte
 4G : 4G Byte 8G : 8G Byte
 AG : 16G Byte BG : 32G Byte
 CG : 64G Byte DG : 128G Byte

6. Composition

1 : NAND1 + Microcontroller
 2 : NAND2 + Microcontroller
 3 : NAND3 + Microcontroller
 4 : NAND4 + Microcontroller
 8 : NAND8 + Microcontroller

7. NAND Small Classification

Code	TYPE	Density
A	MLC	2G Bit
B	MLC	4G Bit
C	MLC	8G Bit
D	MLC	16G Bit
E	MLC	32G Bit
Z	3bit MLC	16G Bit
1	SLC	1G Bit
9	SLC	2G bit(x16 NAND Option)

* A~N : Multi Bit Level Cell (2bit)
 0~Z : Multi Bit Level Cell (3bit, 4bit)
 1~9 : Single Bit Level Cell

8. VCC & VCCQ

Code	VCC	VCCQ	Mode
A	3.3V(2.5V~3.6V)	3.3V(2.5V ~3.6V)	Single
B	2.7V(2.5V~2.9V)	None	Single
C	3.3V(2.5V~3.6V)	1.8V(1.65V~1.95V)	Single
D	1.8V(1.65V~1.95V)	3.3V(2.5V~3.6V)	Single
E	3.3V(2.5V~3.6V)	1.8V(1.65V~1.95V) 3.3V(2.5V ~ 3.6V)	Dual
Q	1.8V(1.7V~1.95V)	None	Single
U	3.3V(2.7V~3.6V)	None	Single

9. Controller

A : S3C49RAA01 D : S3C49VDX01
 E : S3C49VDX03 M : MSP1010
 N : S3C49NBX01 O : S3C49NBX02
 R : S3C49RAX01 S : SK6626
 T : S3C49TBX01 V : S3C49VCX03

10. Component Generation (NAND Generation)

M : 1st Generation A : 2nd Generation
 B : 3rd Generation D : 5th Generation
 E : 6th Generation X : NAND option

11. "-"

12. PKG Type

A : FBGA (Halogen-Free, Lead-Free, OSP) (12*16)
 B : FBGA (Halogen-Free, Lead-Free, OSP)
 S : FBGA (OSP Lead-Free)
 I : LGA (Halogen-Free, Lead-Free)
 L : LGA (Lead-Free)
 P : TSOP (Lead-Free)

13. Revision

0 : None 1 : EVT1
 2 : EVT2 3 : EVT3
 4 : EVT4

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<u>K</u>	<u>L</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

14. Speed

0 : None

15. Reserved

1 : Normal Sample

2 : Premium Sample

* DS : Daisy Chain Sample (14)~(15)

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<u>K</u>	<u>L</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17 18

16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"